



Material Content Data Sheet



Sales Product Name		SPU02N60S5		Issued		1. August 2018		
MA#		MA001077900						
Package		PG-TO251-3-341		Weight*		381.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.473	0.39	0.39	3865	3865
leadframe	inorganic material	phosphorus	7723-14-0	0.069	0.02		180	
	non noble metal	iron	7439-89-6	0.229	0.06		602	
	non noble metal	copper	7440-50-8	228.946	60.09	60.17	600876	601658
	non noble metal	aluminium	7429-90-5	0.410	0.11	0.11	1075	1075
wire	inorganic material	antimonytrioxide	1309-64-4	1.745	0.46		4581	
encapsulation	plastics	brominated resin	-	1.870	0.49		4908	
	organic material	carbon black	1333-86-4	1.995	0.52		5235	
	plastics	epoxy resin	-	16.830	4.42		44170	
	inorganic material	silicondioxide	60676-86-0	102.226	26.83	32.72	268295	327189
leadfinish	non noble metal	tin	7440-31-5	3.740	0.98	0.98	9816	9816
plating	non noble metal	nickel	7440-02-0	0.509	0.13	0.13	1335	1335
solder	non noble metal	tin	7440-31-5	0.036	0.01		93	
	noble metal	silver	7440-22-4	0.044	0.01		117	
	non noble metal	lead	7439-92-1	1.697	0.45	0.47	4455	4665
heatspreader	inorganic material	phosphorus	7723-14-0	0.006	0.00		15	
	non noble metal	iron	7439-89-6	0.019	0.00		50	
	non noble metal	copper	7440-50-8	19.177	5.03	5.03	50332	50397
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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